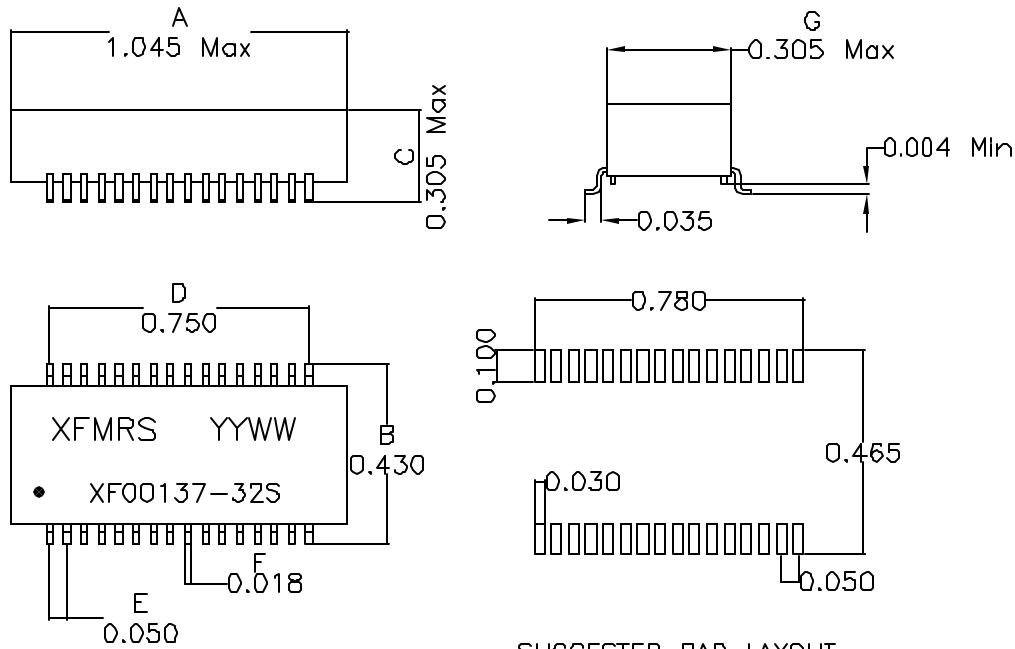
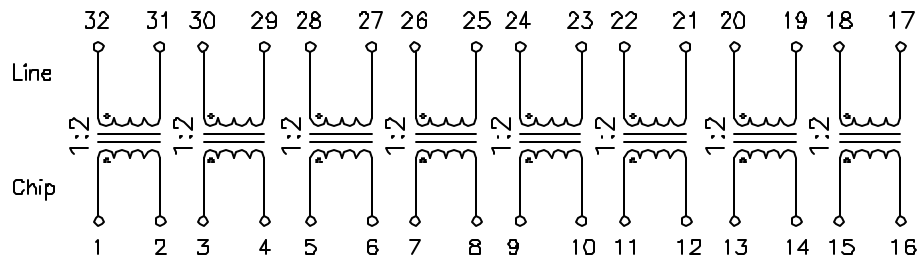


1. Mechanical Dimensions:



SUGGESTED PAD LAYOUT

2. Schematic:



DOC REV: A/5

3. Electrical Specifications: @25°C

Isolation: 1500Vrms (PRI to SEC)

TX & RCV Turns Ratio: 1:2 (Chip:Line)

CHIP OCL: 1.50mH Typ @10KHz 50mV

Cw/w: 35pF Max @10KHz 50mV (Chip/Line)

CHIP LL: 0.3uH Max @1MHz 50mV, Short Line

CHIP DCR: 0.6 Ohms Max

LINE DCR: 1.2 Ohms Max

RETURN LOSS: 24dB Typ @102KHz, 100 Ohms

RETURN LOSS: 29dB Typ @102KHz, 120 Ohms

Notes:

1. Solderability: Leads shall meet MIL-STD-202, Method 208D for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen Index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: $\pm 0.004^{\circ}(0.102\text{mm})$
9. Moisture Sensitivity: Level 2

XFMRS Inc	Title: T1/E1/CEPT QUAD PORT		
	UNLESS OTHERWISE SPECIFIED TOLERANCES:		P/N: XF00137-32S REV. A
.xxx ± 0.010	DWN.	Juan Mao	Sep-07-04
Dimensions in INCH	CHK.	YK Liao	Sep-07-04
SHEET 1 OF 1	APP.	YK Liao	Sep-07-04